AMENDMENTS TO THE CLAIMS:

Complete Listing of Claims

1. (original) An encapsulated chip assembly comprising:

a baseplate (12),

a chip (10) attached to the baseplate in such a way that its contact surfaces (20) face away from the baseplate (12),

a layer (14) of a conductive material applied to the baseplate (12) and arranged to around the chip (10), and which is at least as high as the chip (10),

a cover plate (16) arranged on the layer of conductive material (14), whose one side, opposing the chip (10), being provided with one or more conductive surfaces (18), which are arranged in such a way that they form an electrical connection between the chip (10) and the layer of conductive material (14).

2. (original) The encapsulated chip according to claim 1, whereby the chip (10) is surrounded by a filler material that fills the open space between the baseplate (12) and the cover plate (16).

3. (original) The encapsulated chip according to claim 2, further comprising an electrically conductive glue, which is to establish both the electrical and the mechanical connections between the contact surfaces (20) of the chip (10) and the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16).

4. (original) The encapsulated chip according to claim 2, further comprising an anisotropically conductive film (26) (ACF), which serves to establish both an electrical and a mechanical connection between the contact surfaces (20) of the chip (10) and the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16), and between the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16) and the conductive layer (14) applied to the baseplate (12).

5. (original) The encapsulated chip according to claim 4, whereby the filler material consists of the anisotropically conductive film (26).

6. (original) The encapsulated chip according to claim 1, where both the baseplate (12) and the cover plate (16) each consist of a flexible material.

7. (original) The encapsulated chip according to claim1, where the height of the chip (10) is so low that it is rendered flexible.

8. (original) The encapsulated chip according to claim 7, where the chip (10) consists mainly of silicon and has a thickness of less than 50 ìm.

9. (original) The encapsulated chip according to claim 1, where the chip (10) comprises a transponder.

10. (original) The encapsulated chip according to claim 9, where the conductive layer (14) comprises an aerial.

11. (original) An encapsulated chip assembly for a smart label comprising:

a flexible baseplate (12),

a chip (10) having a transponder attached to the baseplate in such a way that its contact surfaces (20) face away from the baseplate (12),

a layer (14) of a conductive material applied to the baseplate (12) and arranged to around the chip (10), and which is at least as high as the chip (10) and forms an aerial for electrical signals for the transponder,

a cover plate (16) arranged on the layer of conductive material (14), whose one side, opposing the chip (10), being provided with one or more conductive surfaces (18), which are arranged in such a way that they form an electrical connection between the chip (10) and the layer of conductive material (14).

12. (original) The encapsulated chip according to claim 11, further comprising an electrically conductive glue, which is to establish both the electrical and the mechanical connections between the contact surfaces (20) of the chip (10) and the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16).

13. (original) The encapsulated chip according to claim 12, further comprising an anisotropically conductive film (26) (ACF), which serves to establish both an electrical and a mechanical connection between the contact surfaces (20) of the chip (10) and the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16), and between the conductive surface (18) or the conductive surfaces (18), respectively, of the cover plate (16) and the conductive layer (14) applied to the baseplate (12).

14. (original) The encapsulated chip according to claim 11, where the height of the chip (10) is so low that it is rendered flexible.

15. (original) The encapsulated chip according to claim 14, where the chip (10) consists mainly of silicon and has a thickness of less than 50 µm.

Please cancel Claims 16-20.